



IN THE CLAIMS

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MAY 31 2001
TECHNOLOGY CENTER 2880

1. (Three Times Amended) A method of removing a particle from a surface of a metal plug formed in a via comprising:
introducing a first agent to a metal layer;
polishing the metal layer with the first agent;
after polishing the metal layer, introducing a second agent comprising hydrogen peroxide to rinse the surface of the metal plug; and
removing at least one particle from the surface of the metal plug.

9. (Three Times Amended) A method of removing at least one particle from a surface of a metal plug disposed over a substrate comprising:
depositing a slurry onto a metal layer over the metal plug;
polishing the metal layer; and
after polishing the metal layer, rinsing the surface of the metal plug with a solution comprising hydrogen peroxide.

18. (Three Times Amended) A method comprising:
polishing a metal layer over a conductive plug with a slurry;
after polishing the metal layer, introducing a rinsing solution onto the conductive plug, the rinsing solution comprises hydrogen peroxide.